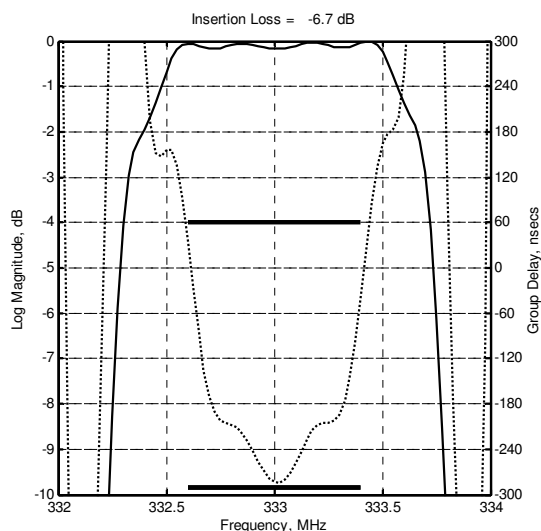
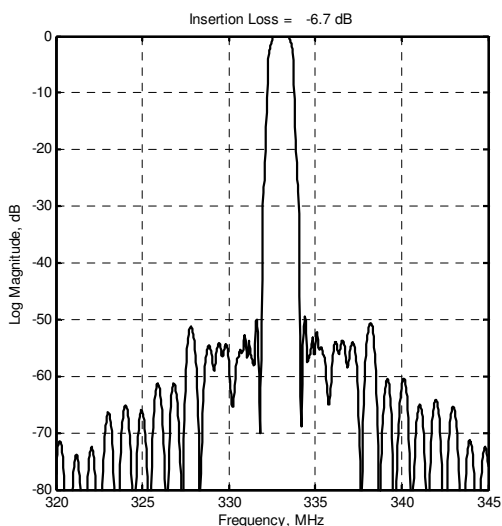


Preliminary Datasheet (Simulation)



Specifications

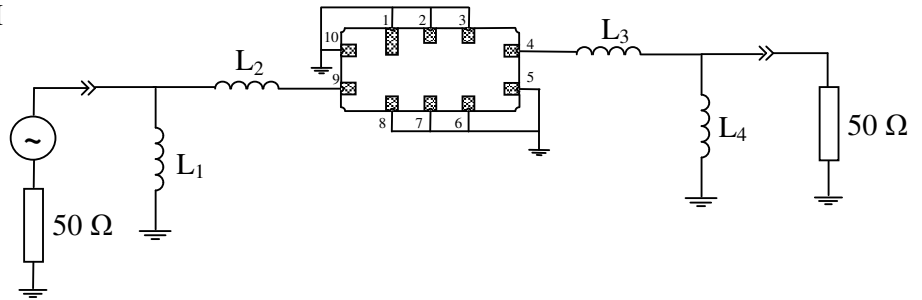
Parameter	Unit	Min	Typ	Max	Note
Center Frequency f_o	MHz		333		
Insertion Loss at f_o	dB		6.7	8	Matched, Q=30
Passband Width	MHz				
-3 dB			1.34		
-20 dB			1.77		
-30 dB			2.07		
-40 dB			2.15		
-50 dB			2.21		
Relative Attenuation	dB				
f_o-50 MHz ... f_o-3 MHz			-50		
f_o+3 MHz ... f_o+20 MHz			50		
f_o+20 MHz ... f_o+40 MHz			64		
f_o+40 MHz ... f_o+50 MHz			70		
Passband Ripple	dB		0.25	1	At $f_o \pm 0.4$ MHz (p-p)
Phase Linearity	degs		5	8	At $f_o \pm 0.4$ MHz (p-p)
Group Delay Variation	nsecs		350	500	At $f_o \pm 0.4$ MHz (p-p)
Absolute Group Delay	μ sec		1.1		
Reflected Wave Signal Suppression	dB		60		12 ... 20 μ sec after main pulse
Substrate Material			Quartz		
Temperature Coefficient of Frequency (TCF)*	ppm/ $^{\circ}$ C ²		-0.036		
Turnover Temperature	$^{\circ}$ C		15		
Operating Temperature	$^{\circ}$ C	-55	25	85	
Storage Temperature	$^{\circ}$ C	-55		85	
Package Size	mm		9.1 x 4.5		SMD

* Temperature dependence

$$f_o(T) = f_o(T_o)(1 + TCF(T - T_o)^2)$$

Matching Configuration

$L_1 = 8.2 \text{ nH}$, $L_2 = 15 \text{ nH}$
 $L_3 = 15 \text{ nH}$, $L_4 = 11 \text{ nH}$
Source/Load
Impedance = 50Ω



Time Response

